



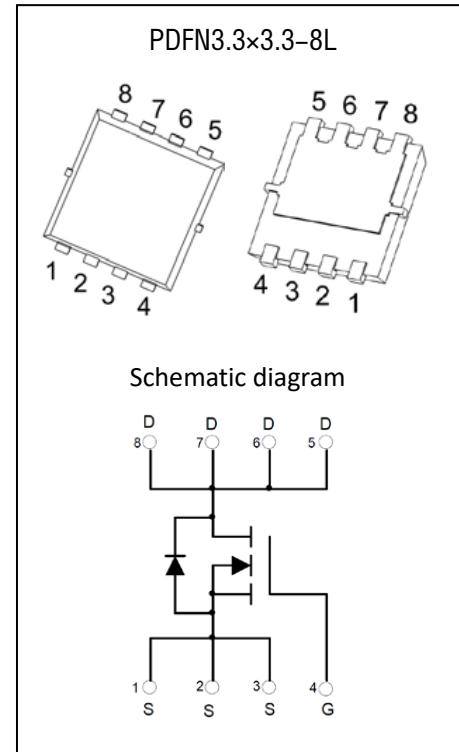
GP
ELECTRONICS

GP40N04P33

40V N-Channel MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	5.5mΩ@10V	40A
	7.1mΩ@4.5V	



Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Switching Application

MARKING:



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	40	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	40	A
	I_D	26	A
Pulsed Drain Current ²	I_{DM}	80	A
Single Pulsed Avalanche Current ³	I_{AS}	13	A
Single Pulsed Avalanche Energy ³	E_{AS}	41	mJ
Power Dissipation ⁵	P_D	12.5	W
Thermal Resistance from Junction to Ambient ⁶	$R_{\theta JA}$	30.2	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55~+150	°C

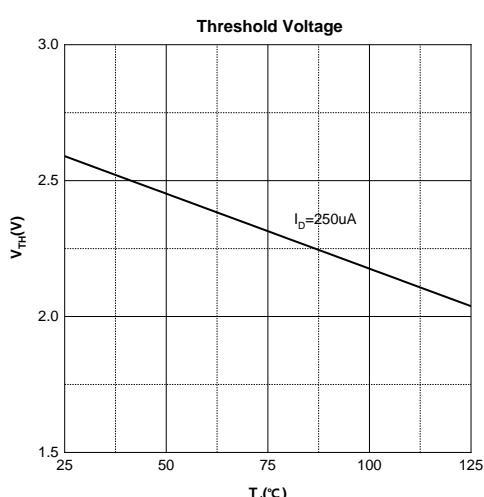
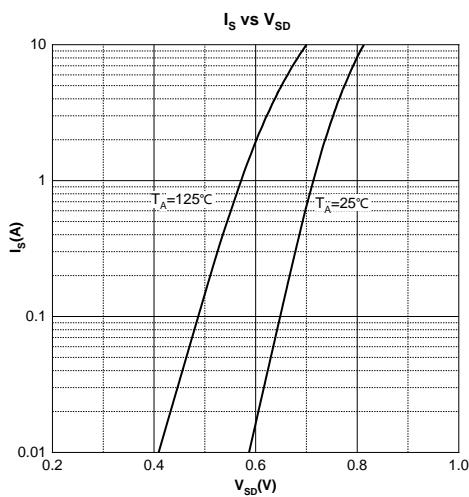
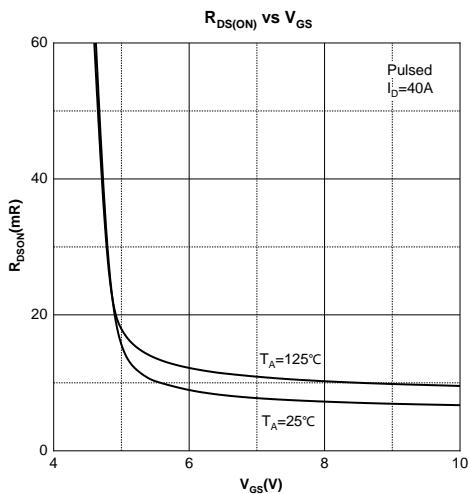
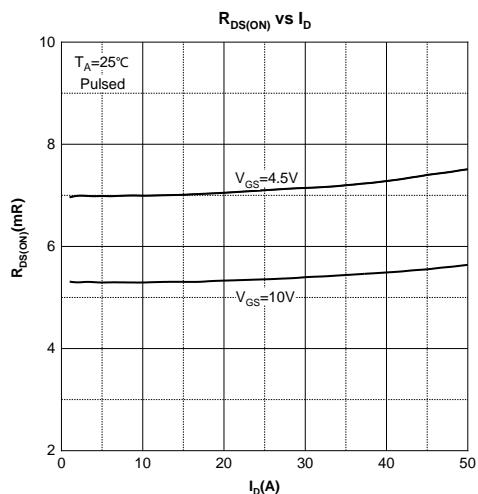
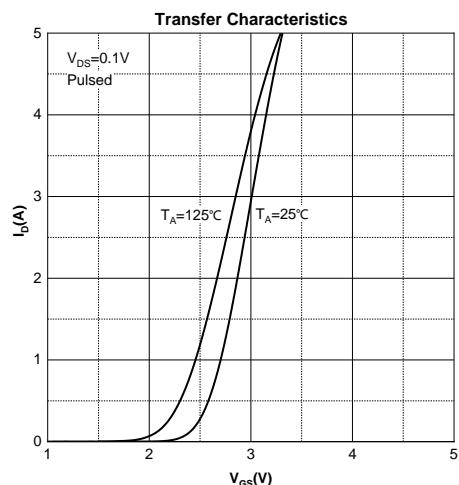
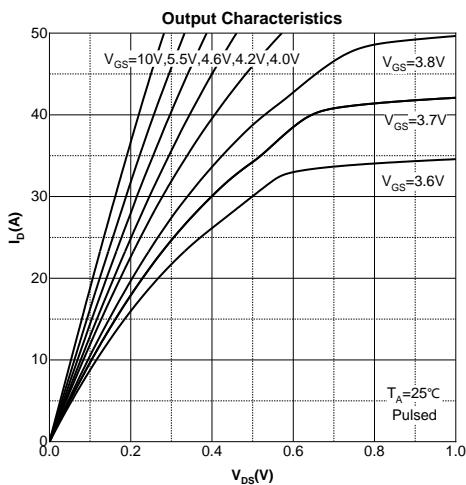
MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

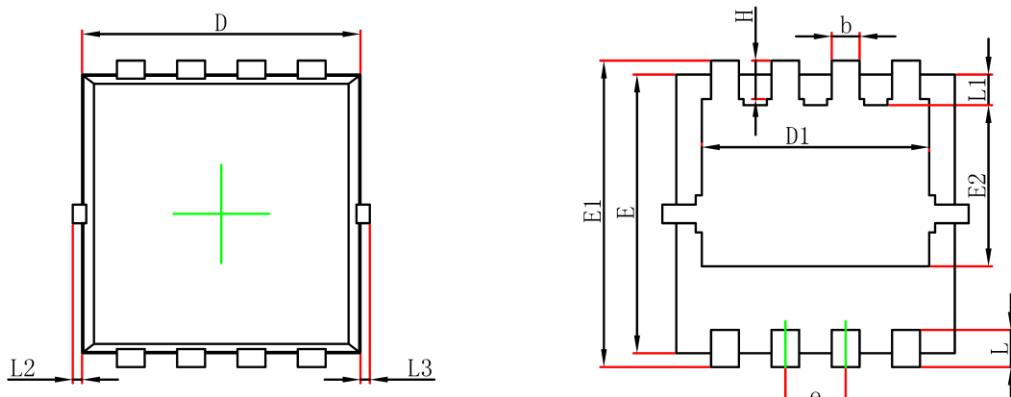
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			± 100	nA
On Characteristics⁴						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	1.9	3	V
Drain-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 12\text{A}$		5.5	7.2	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$		7.1	11	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		2974		pF
Output Capacitance	C_{oss}			279		
Reverse Transfer Capacitance	C_{rss}			253		
Gate Resistance	R_g	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		1.5		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{\text{DS}} = 32\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 40\text{A}$		25		nC
Gate-source Charge	Q_{gs}			5.2		
Gate-drain Charge	Q_{gd}			3.6		
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{\text{DD}} = 20\text{V}, V_{\text{GS}} = 10\text{V}, R_G = 4.7\Omega, R_G = 1.8\Omega$		5		ns
Turn-on Rise Time	t_r			25		
Turn-off Delay Time	$t_{d(\text{off})}$			35		
Turn-off Fall Time	t_f			13		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_s = 10\text{A}$			1.2	V

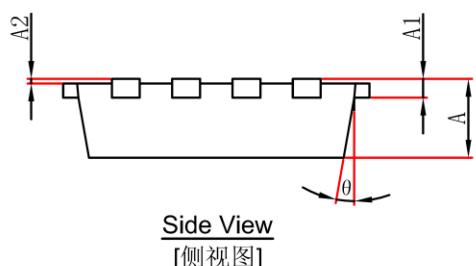
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.E_{AS} condition: $V_{\text{DD}} = 24\text{V}, V_{\text{GS}} = 20\text{V}, L = 0.1\text{mH}, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(\text{MAX})} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics



PDFN3.3x3.3-8L Package Information

Top View
[顶视图]

Bottom View
[背视图]

Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.152REF		0.006REF	
A2	0.000	0.050	0.000	0.002
D	2.900	3.200	0.114	0.126
D1	2.300	2.600	0.091	0.102
E	2.900	3.200	0.114	0.126
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0.000	0.100	0.000	0.004
L3	0.000	0.100	0.000	0.004
H	0.315	0.515	0.012	0.020
θ	0°	12°	0°	12°